

SN54ALS534A, SN74ALS534A, SN74AS534 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS

SDAS168B – APRIL 1982 – REVISED JULY 1996

- 3-State Bus Driving Inverting Outputs
- Buffered Control Inputs
- Package Options Include Plastic Small-Outline (DW), Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

These octal D-type edge-triggered flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

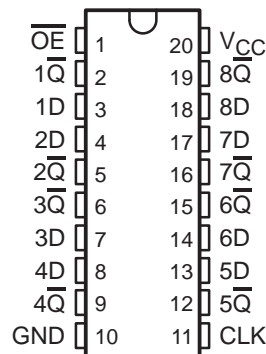
On the positive transition of the clock (CLK) input, the \bar{Q} outputs are set to the complement of the logic states set up at the data (D) inputs. The 'ALS534A and SN74AS534 have inverted outputs, but otherwise are functionally equivalent to the 'ALS374A and SN74AS374.

A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

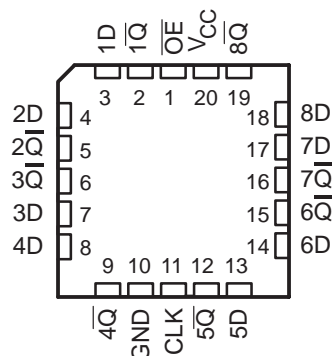
\overline{OE} does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are off.

The SN54ALS534A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS534A and SN74AS534 are characterized for operation from 0°C to 70°C .

SN54ALS534A . . . J PACKAGE
SN74ALS534A, SN74AS534 . . . DW OR N PACKAGE
(TOP VIEW)



SN54ALS534A . . . FK PACKAGE
(TOP VIEW)



FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
\overline{OE}	CLK	D	\bar{Q}
L	\uparrow	H	L
L	\uparrow	L	H
L	H or L	X	\bar{Q}_0
H	X	X	Z



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
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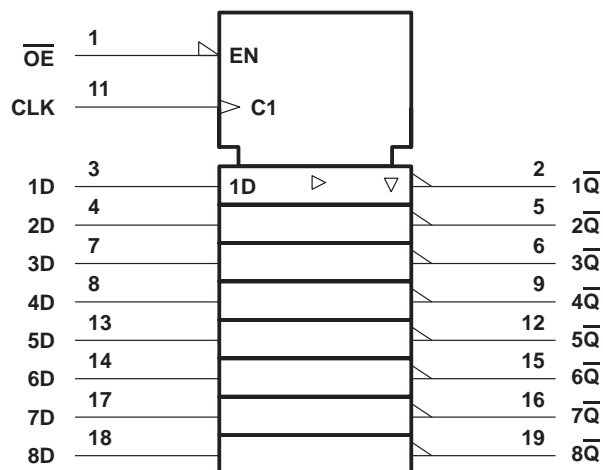
SN54ALS534A, SN74ALS534A, SN74AS534

OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS

WITH 3-STATE OUTPUTS

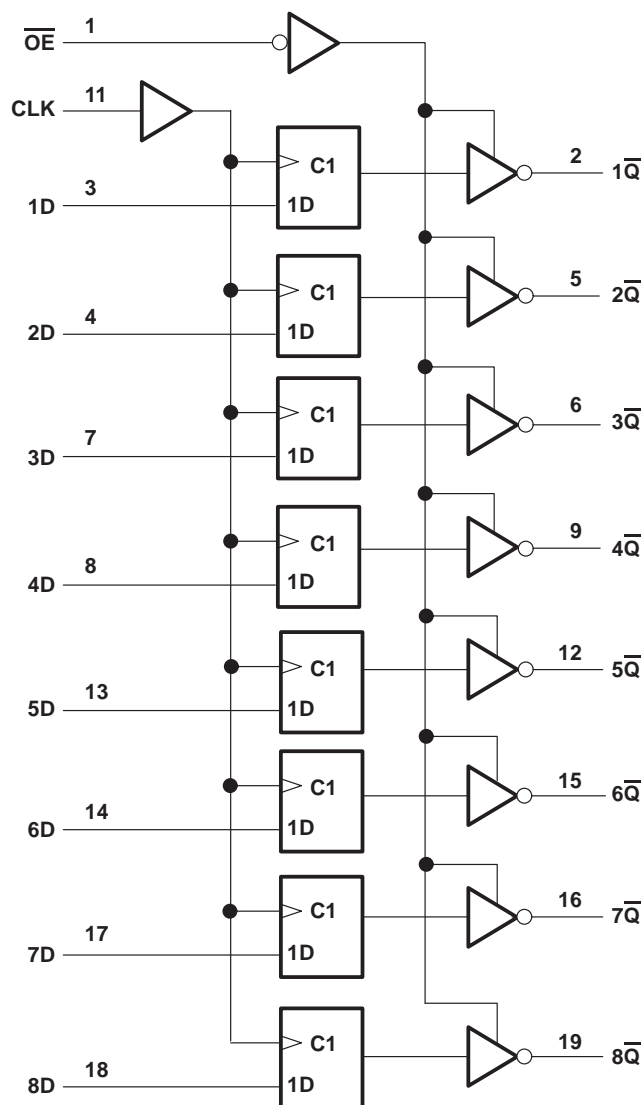
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



SN54ALS534A, SN74ALS534A, SN74AS534

OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS

WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T_A : SN54ALS534A	–55°C to 125°C
SN74ALS534A	0°C to 70°C
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS534A			SN74ALS534A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			–1			–2.6	mA
I_{OL}	Low-level output current			12			24	mA
f_{clock}	Clock frequency	0		30	0		35	MHz
t_w	Pulse duration, CLK high or low	16.5			14			ns
t_{su}	Setup time, data before CLK \uparrow	10			10			ns
t_h	Hold time, data after CLK \uparrow	0			0			ns
T_A	Operating free-air temperature	–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS534A			SN74ALS534A			UNIT
				MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$				–1.5			–1.5	V
V_{OH}		$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -0.4\text{ mA}$		$V_{CC} - 2$			$V_{CC} - 2$			V
		$V_{CC} = 4.5\text{ V}$, $I_{OH} = -1\text{ mA}$		2.4	3.3					
		$V_{CC} = 4.5\text{ V}$, $I_{OH} = -2.6\text{ mA}$					2.4	3.2		
V_{OL}		$V_{CC} = 4.5\text{ V}$, $I_{OL} = 12\text{ mA}$			0.25	0.4		0.25	0.4	V
		$V_{CC} = 4.5\text{ V}$, $I_{OL} = 24\text{ mA}$						0.35	0.5	
I_{OZH}		$V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$				20			20	μA
I_{OZL}		$V_{CC} = 5.5\text{ V}$, $V_O = 0.4\text{ V}$				–20			–20	μA
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$				0.1			0.1	mA
I_{IH}		$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$				20			20	μA
I_{IL}	CLK, \overline{OE}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$				–0.1			–0.1	mA
	D					–0.2			–0.2	
I_{OS}^{\S}		$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$		–20		–112	–30		–112	mA
I_{CC}		$V_{CC} = 5.5\text{ V}$, Outputs high			11	19		11	19	mA
		$V_{CC} = 5.5\text{ V}$, Outputs low			19	28		19	28	
		$V_{CC} = 5.5\text{ V}$, Outputs disabled			10	31		20	31	

[‡] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

^{\S} The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .



SN54ALS534A, SN74ALS534A, SN74AS534

OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS

WITH 3-STATE OUTPUTS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54ALS534A		SN74ALS534A		
			MIN	MAX	MIN	MAX	
f _{max}			30		35		MHz
t _{PLH}	CLK	Any \overline{Q}	3	17	3	12	ns
t _{PHL}			4	18	4	16	
t _{PZH}	\overline{OE}	Any \overline{Q}	3	19	3	17	ns
t _{PZL}			4	20	4	18	
t _{PHZ}	\overline{OE}	Any \overline{Q}	1	12	1	10	ns
t _{PLZ}			1	25	2	14	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN74AS534	0°C to 70°C
Storage temperature range, T _{stg}	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74AS534			UNIT
		MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			–15	mA
I _{OL}	Low-level output current			48	mA
f _{clock}	Clock frequency	0		125	MHz
t _w	Pulse duration	CLK high		4	ns
		CLK low		3	
t _{su}	Setup time, data before CLK↑	2			ns
t _h	Hold time, data after CLK↑	2			ns
T _A	Operating free-air temperature	0		70	°C



SN54ALS534A, SN74ALS534A, SN74AS534

OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN74AS534			UNIT
		MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2	V
V_{OH}	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -2\text{ mA}$	$V_{CC} - 2$			V
	$V_{CC} = 4.5\text{ V}$, $I_{OH} = -15\text{ mA}$	2.4	3.3		
V_{OL}	$V_{CC} = 4.5\text{ V}$, $I_{OL} = 48\text{ mA}$		0.34	0.5	V
I_{OZH}	$V_{CC} = 5.5\text{ V}$, $V_O = 2.7\text{ V}$			50	μA
I_{OZL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$			-50	μA
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$			0.1	mA
I_{IH}	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$			20	μA
I_{IL}	\overline{OE} , CLK			-0.5	mA
	D			-2	
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$			-30	mA
I_{CC}	$V_{CC} = 5.5\text{ V}$	Outputs high		77	mA
		Outputs low		84	
		Outputs disabled		84	

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

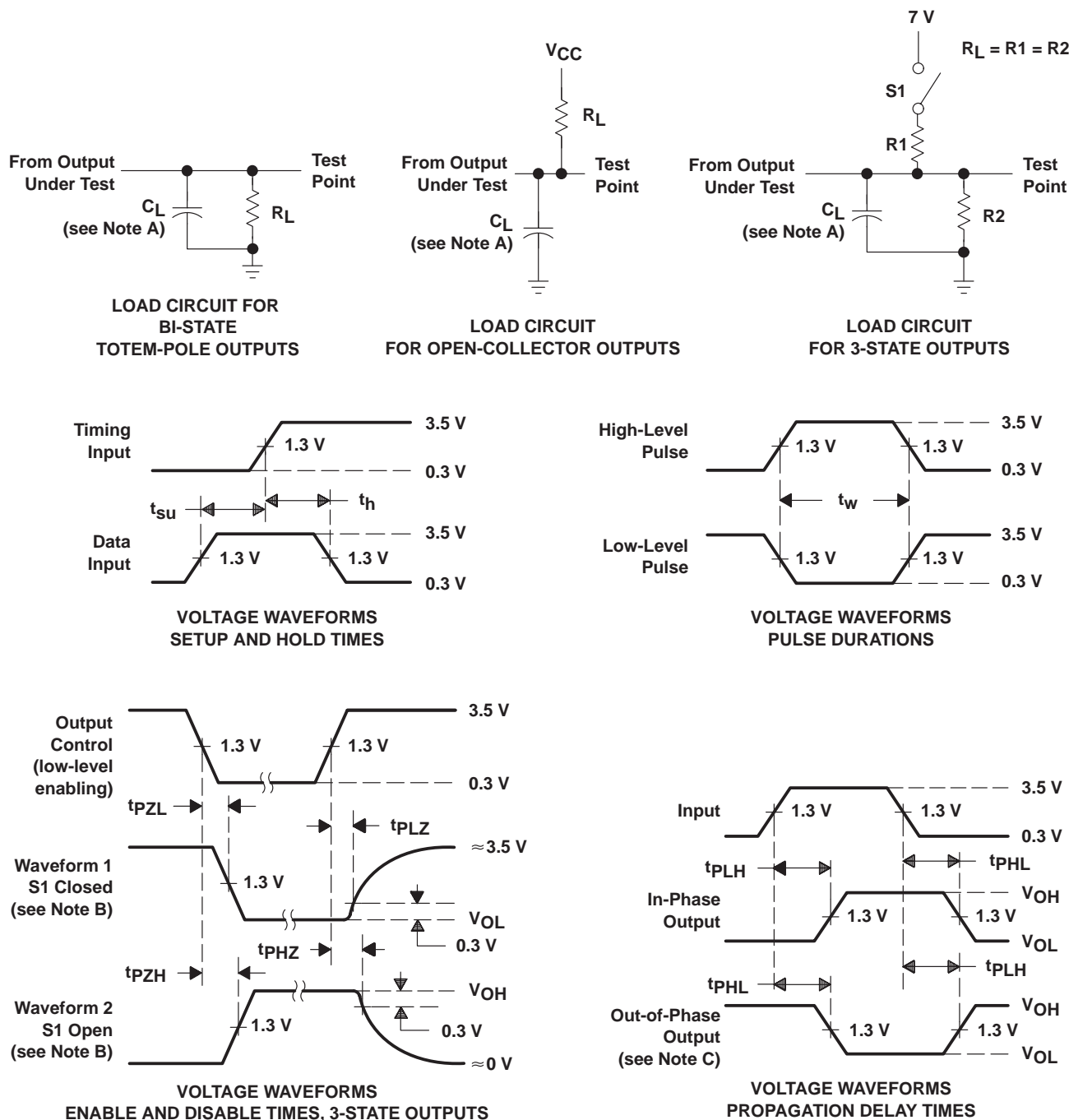
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T _A = MIN to MAX§		UNIT
			SN74AS534		
			MIN	MAX	
f _{max}			125		MHz
t _{PLH}	CLK	Any \overline{Q}	3	8	ns
t _{PHL}			4	9	
t _{PZH}	\overline{OE}	Any \overline{Q}	2	6	ns
t _{PZL}			3	10	
t _{PHZ}	\overline{OE}	Any \overline{Q}	2	6	ns
t _{PLZ}			2	6	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

SN54ALS534A, SN74ALS534A, SN74AS534 OCTAL D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - When measuring propagation delay items of 3-state outputs, switch S1 is open.
 - All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 - The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54ALS534J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		
SN74ALS534ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS534A	Samples
SN74ALS534ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS534A	Samples
SN74ALS534AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS534AN	Samples
SN74ALS534AN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS534ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS534A	Samples
SN74AS534DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS534DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS534N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SNJ54ALS534FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
SNJ54ALS534J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74ALS534A :

- Military: [SN54ALS534A](#)

NOTE: Qualified Version Definitions:

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS534ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS534ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



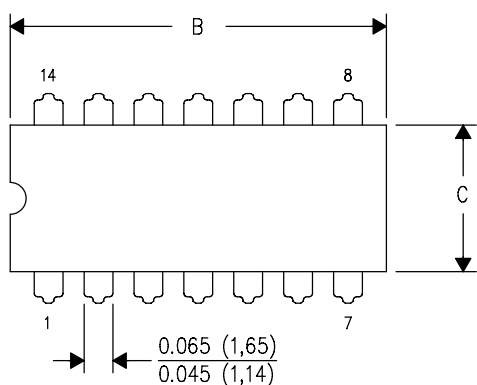
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS534ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS534ANSR	SO	NS	20	2000	367.0	367.0	45.0

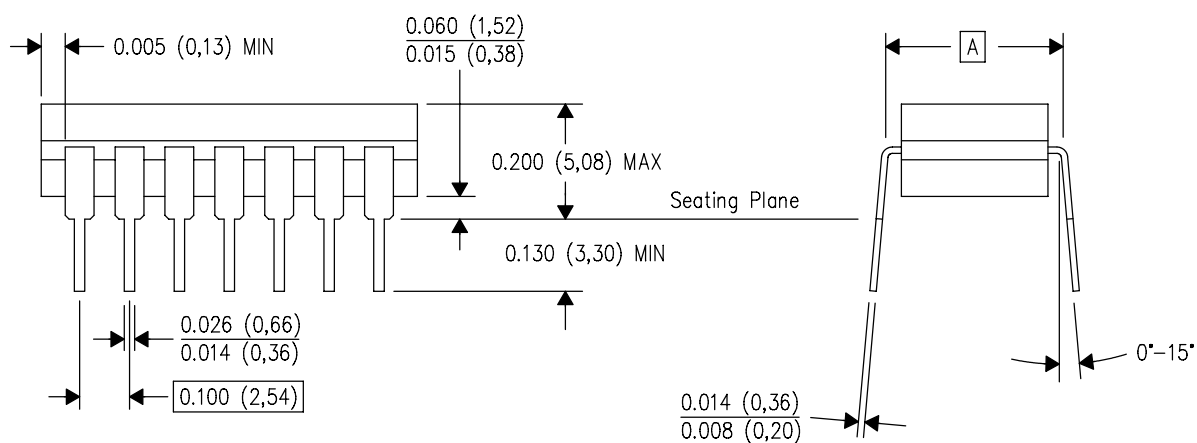
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



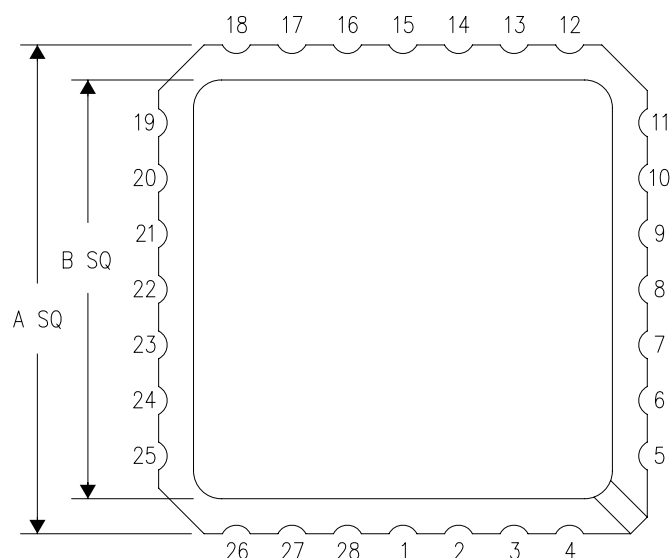
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

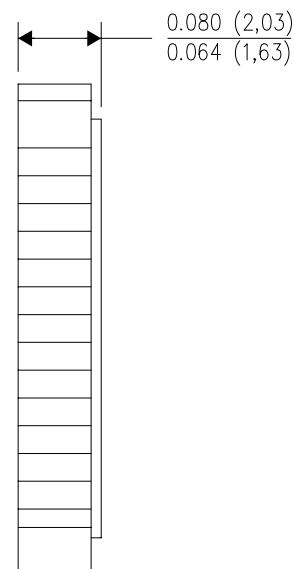
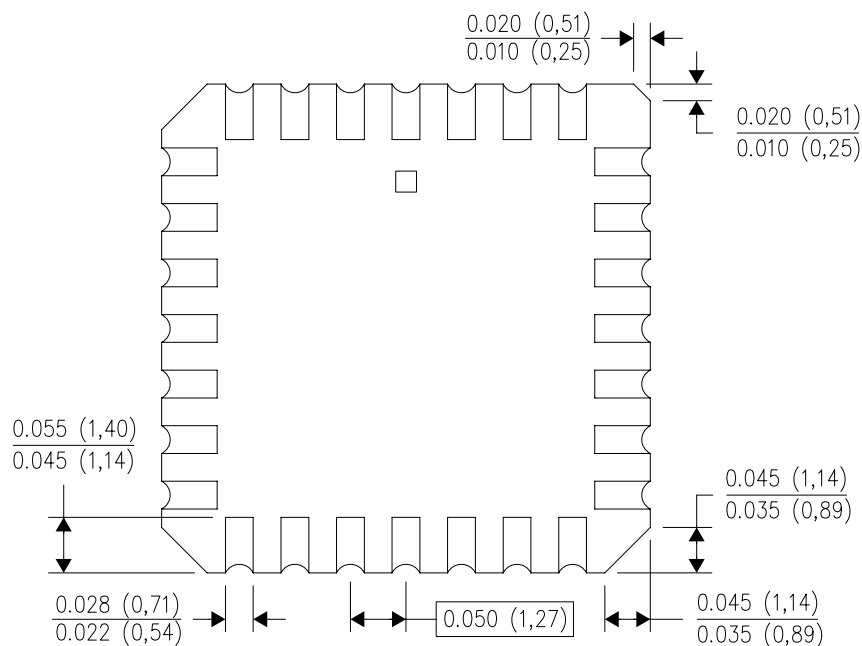
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



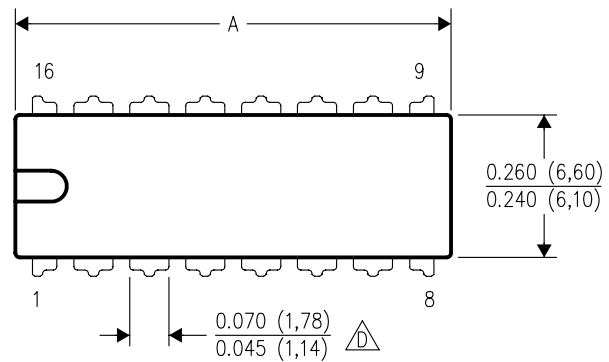
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

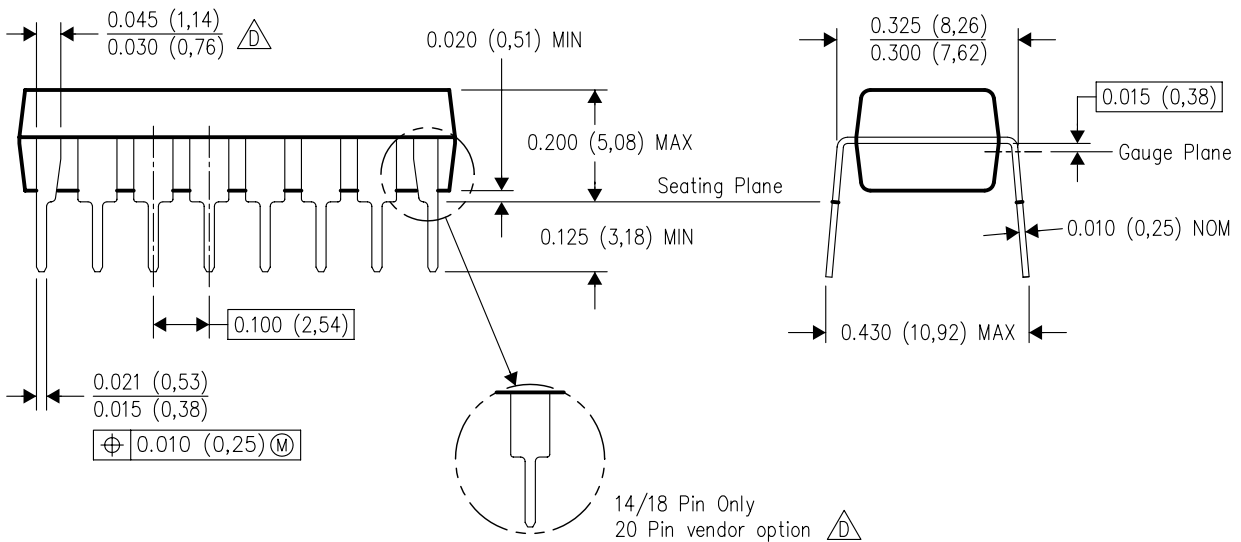
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



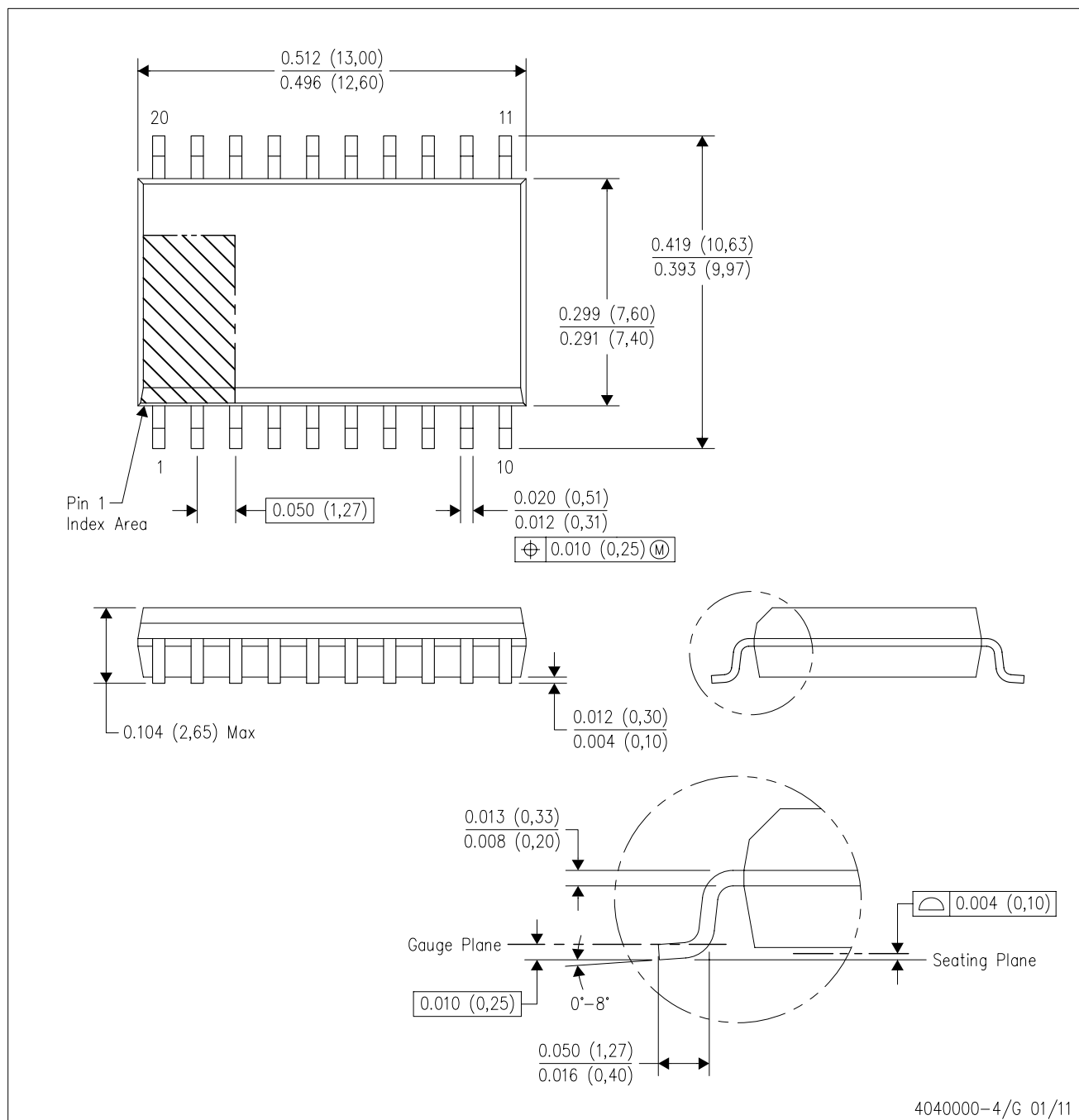
14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

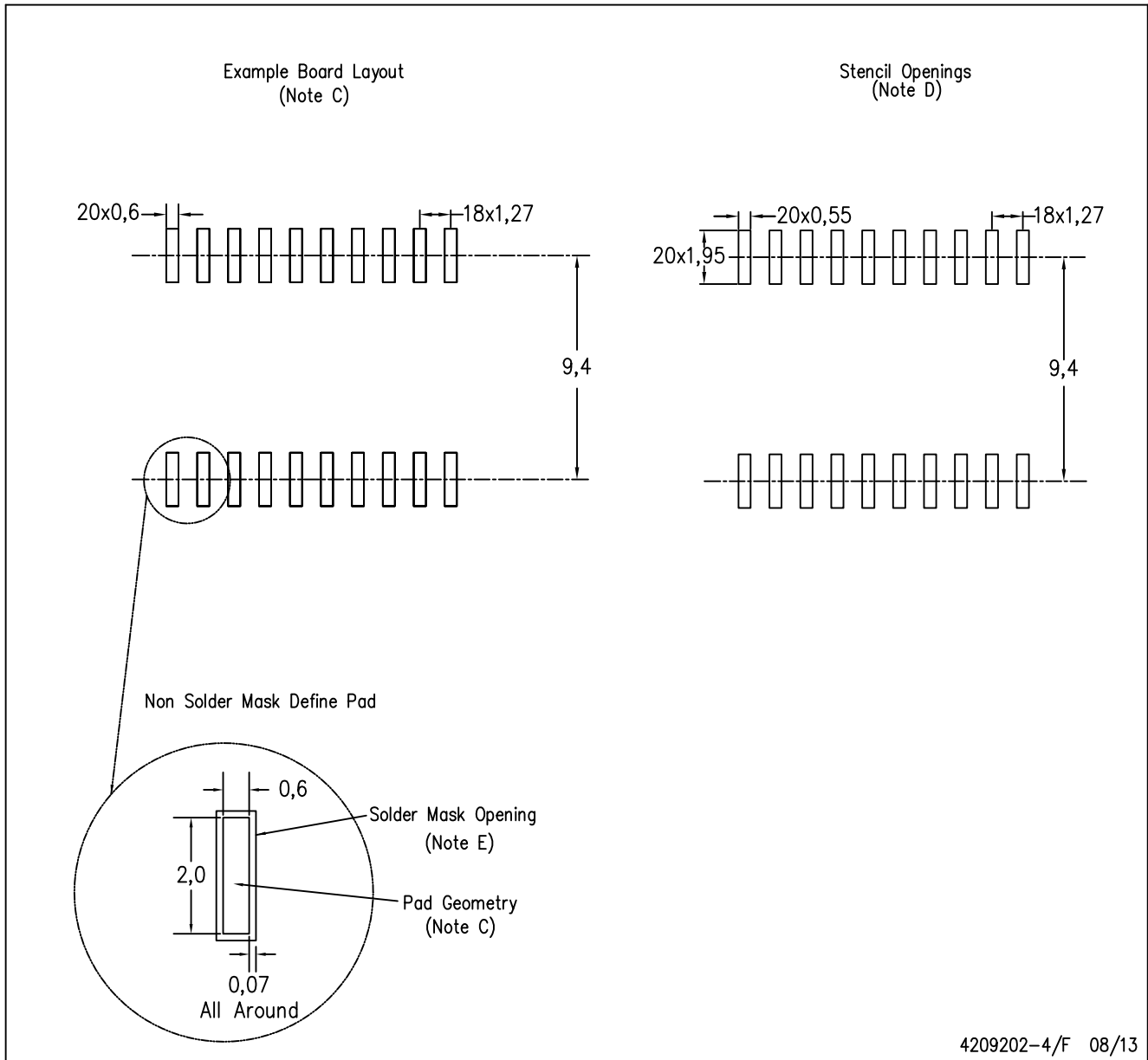
PLASTIC SMALL OUTLINE



- NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



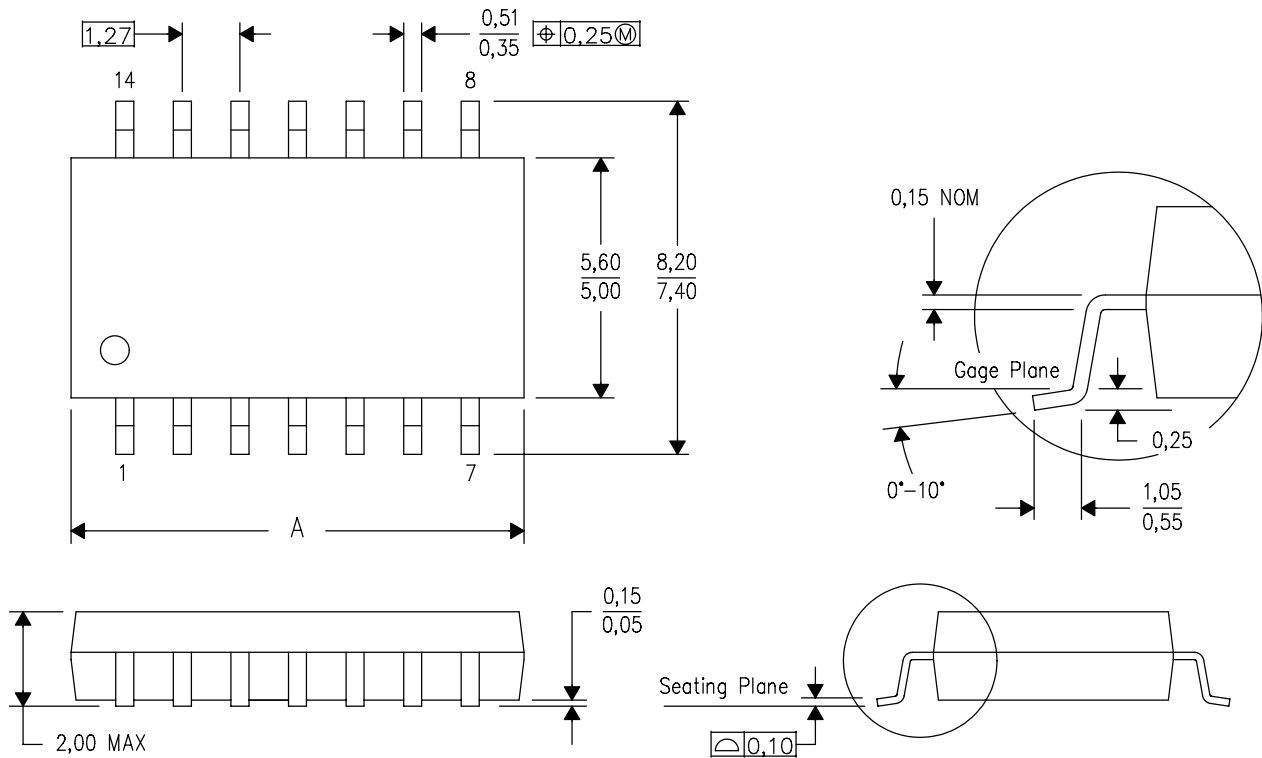
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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